8 x 8-bit Parallel Multiplier

LMU08/LMU8U

FEATURES

- ☐ 35 ns Worst-Case Multiply Time
- ☐ Low Power CMOS Technology
- ☐ LMU08 Replaces TRW MPY008H
- ☐ LMU8U Replaces TRW MPY08HU
- Two's Complement (LMU08), or Unsigned Operands (LMU8U)
- ☐ Three-State Outputs
- ☐ Available Screened to MIL-STD-883, Class B
- ☐ Package Styles Available:
 - 40-pin Plastic DIP
 - 40-pin Sidebraze, Hermetic DIP
 - 44-pin Plastic LCC, J-Lead (LMU08 only)
 - 44-pin Ceramic LCC (Type C)

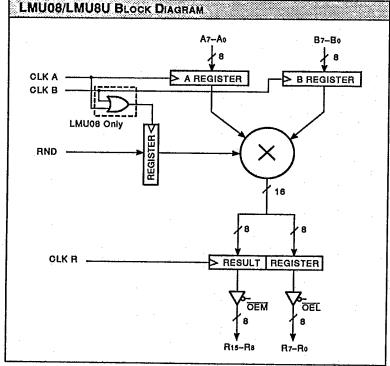
DESCRIPTION

The LMU08 and LMU8U are 8-bit parallel multipliers which feature high speed with low power consumption. They are pin-for-pin equivalents with TRW MPY08H and MPY008HU type multipliers. Full military ambient temperature range operation is attained by the use of advanced CMOS technology.

Both the LMU08 and the LMU8U produce the 16-bit product of two 8-bit numbers. The LMU08 accepts operands in two's complement format, and produces a two's complement result. The product is provided in two halves with the sign bit replicated as the most significant bit of

both halves. This facilitates use of the LMU08 product as a double precision operand in 8-bit systems. The LMU8U operates on unsigned data, producing an unsigned magnitude result.

Both the LMU08 and the LMU8U feature independently controlled registers for both inputs and the product, which along with three-state outputs allows easy interfacing with microprocessor busses. Provision is made in the LMU08 and LMU8U for proper rounding of the product to 8-bit precision. The round input is loaded at the rising edge of the logical OR of CLK A and CLK B for the LMU08. The LMU8U latches RND on the rising edge of CLK A only. In either case, a '1' is added in the most significant position of the lower product byte when RND is asserted. Subsequent truncation of the least significant product byte results in a correctly rounded 8-bit result.



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8 x 8-bit Parallel Multiplier

7 6 5 🐡 2 1 0

22 21 20

27 26 25

7 6 5 🗰 2 1 0

27 26 25

22 21 20

T-45-07 INPUT FORMATS - LUM08 Fractional Two's Complement 7 6 5 🗰 2 1 0 7 6 5 🗰 2 1 0 -2° 2-1 2-2 2-5 2-6 2-7 -20 2-1 2-2 2-5 2-6 2-7 (Sign) (Sign) -- LMU08 Integer Two's Complement-7 6 5 🗰 2 1 0 7 6 5 🗰 2 1 0 -27 26 25 22 21 20 22 21 20 -27 26 25 (Sign) (Sign) __ LMU8U Unsigned Fractional -7 6 5 2 1 0 2-1 2-2 2-3 2-6 2-7 2-8 2-1 2-2 2-3 --- LMU8U Unsigned integer --

OUTPUT FOR	IMATS		
	MSP	LSP	
	LMU08 Fractional T	wo's Complement	
	15 14 13 ₩ 10 9 8	7 6 5 🗰 2 1 0	
	-2° 2-1 2-2 2-5 2-6 2-7 (Sign)	-2° 2-8 2-9 2-12 2-13 2-14 (Sign)	
	LMU08 Integer Tw	o's Complement	
	15 14 13 10 9 8 -2 ¹⁴ 2 ¹³ 2 ¹² 2 ⁹ 2 ⁸ 2 ⁷ (Sign)	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	
·	LMU8U Unsign	ed Fractional	
	15 14 13 10 9 8 2-1 2-2 2-3 2-6 2-7 2-8	7 6 5 0 2 1 0 2-9 2-10 2-11 2-14 2-15 2-16	
	LMU8U Unsi	gned Integer ————	
	15 14 13 10 9 8 215 214 213 210 29 28	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	

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Storage temperature	65°C to +150°C
Operating ambient temperature	
Vcc supply voltage with respect to ground	
nput signal with respect to ground	
Signal applied to high impedance output	
Output current into low outputs	25 mA
Latchup current	

	d switching characteristics

Mode

Temperature Range (Ambient)

Supply Voltage

Active Operation, Commercial

0°C to +70°C

4.75 V ≤ Vcc ≤ 5.25 V

Active Operation, Military

-55°C to +125°C

4.50 V ≤ Vcc ≤ 5.50 V

ELECTRI	CAL CHARACTERISTICS O	ver Operating Conditions				
Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V OH	Output High Voltage	IOH = -2.0 mA	3.5			V
V OL	Output Low Voltage	IOL = 8.0 mA			0.5	V
Уін	Input High Voltage		2.0		Vcc	V
VIL,	Input Low Voltage	(Note 3)	0.0		0.8	٧
lix	Input Current	Ground ≤ VIN ≤ Vcc			±20	μА
loz	Output Leakage Current	Ground ≤ Vout ≤ Vcc			±20	μА
los	Output Short Current	Vout = Ground, Vcc = Max (Notes 4, 8)			-250	mA
ICC1	Vcc Current, Dynamic	(Notes 5, 6)		8	24	mA
lcc2	Vcc Current, Quiescent	(Note 7)			1.0	mA

Logic

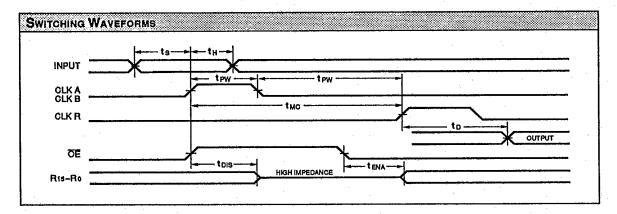
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SWITCHING CHARACTERISTICS

8 x 8-bit Parallel Multiplier

<u> </u>	Parameter	LMU08/LMU8U-						
		7	70		50		35	
Symbol		Min	Max	Min	Mex	Min	Mex	
tMC	Multiply Time (Clocked)		70		50		35	
tD	Output Delay		25		20		18	
tENA	Output Enable Time (Note 11)		20		18		18	
tDIS	Output Disable Time (Note 11)		18		17		17	
tpw.	Clock Pulse Width	20		20		10		
tH	Input Register Hold Time	4		0		0		
ts	Input Register Setup Time	14	T	14		14		

	Parameter	LMU08/LMU8U-					
		9	90		60		5
Symbol		Min	Mex	Min	Mex	Min	Mex
tMC	Multiply Time (Clocked)		90		60		45
t D	Output Delay		35		20		20
tena	Output Enable Time (Note 11)		35		20		20
tois	Output Disable Time (Note 11)		35		18		18
tpw	Clock Pulse Width	25		20		15	
tH	Input Register Hold Time	5		0		0	
ts	Input Register Setup Time	20	<u> </u>	15	T	15	



NOTES

1. Maximum Ratings indicate stress specifications only. Functional operation of these products at values beyond those indicated in the Operating Conditions table is not implied. Exposure to maximum rating conditions for extended periods may affect reliability.

2. The products described by this specification include internal circuitry designed to protect the chip from damaging substrate injection currents and accumulations of static charge. Nevertheless, conventional precautions should be observed during storage, handling, and use of these circuits in order to avoid exposure to excessive electrical stress values.

3. This device provides hard clamping of transient undershoot and overshoot. Input levels below ground or above VCC will be clamped beginning at -0.6 V and VCC + 0.6 V. The device can withstand indefinite operation with inputs in the range of -3.0 V to +7.0 V. Device operation will not be adversely affected, however, input current levels will be well in excess of 100 mA.

4. Duration of the output short circuit should not exceed 30 seconds.

tion can be accurately approximated by:

NCV2F

where

N = total number of device outputs

C = capacitive load per output

V = suppy voltage

F = clock frequency

6. Tested with all outputs changing every cycle and no load, at a 5 MHz

7. Tested with all inputs within 0.1 V of VCC or Ground, no load.

8. These parameters are guaranteed but not 100% tested.

9. AC specifications tested with input transition times less than 3 ns, output reference levels of 1.5 V (except tEN/ tDIS test) and input levels of nominally 0 to 3.0 V. Output loading is a resistive divider which provides for specified IOL and IOH plus 30 pF capacitance.

This device has high speed outputs capable of large instantaneous current pulses and fast turn-on/turn-off times. As a result, care must be exercised in the testing of this device. The following measures are recommended:

5. Supply current for a given applica- a. A 0.1 µF ceramic capacitor should be installed between VCC and Ground leads as close to the Device Under Test (DUT) as possible. Similar capacitors should be installed between device VCC and the tester common, and device ground and tester common.

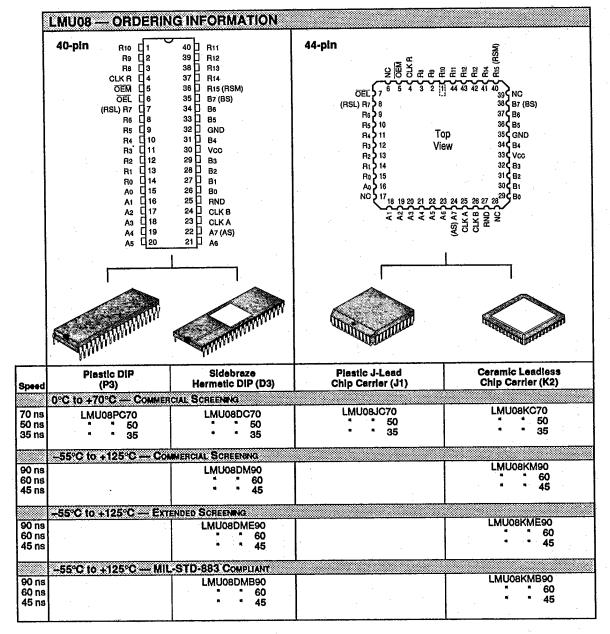
> b. Ground and VCC supply planes must be brought directly to the DUT socket or contactor fingers.

c. Input voltages should be adjusted to compensate for inductive ground and VCC noise to maintain required DUT input levels relative to the DUT ground

10. Each parameter is shown as a minimum or maximum value. Input requirements are specified from the point of view of the external system driving the chip. Setup time, for example, is specified as a minimum since the external system must supply at least that much time to meet the worst-case requirements of all parts. Responses from the internal circuitry are specified from the point of view of the device. Output delay, for example, is specified as a maximum since worst-case operation of any device always provides data within that time.

11. Transition is measured ±200 mV from steady-state voltage with specified loading.



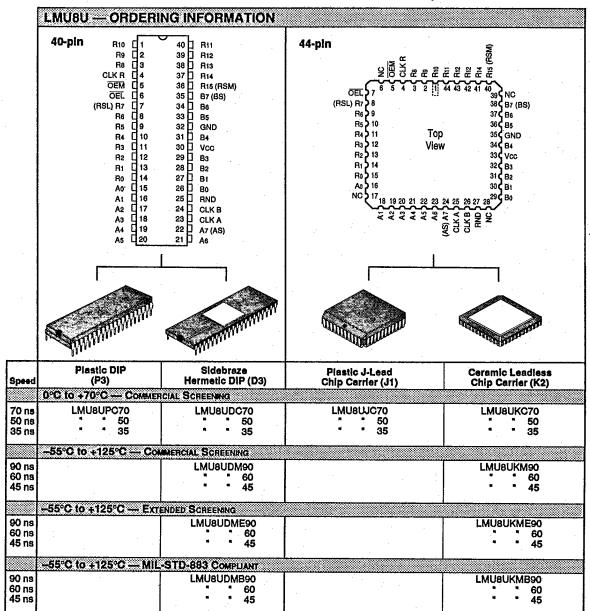




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LDS.08/8U-B